

Application No.: 09/741,684

Amendment After Final dated: January 16, 2007

Reply to Office Action dated: November 14, 2006

RECEIVED  
CENTRAL FAX CENTER

1-18 (Cancelled)

JAN 16 2007

AMENDMENTS TO THE CLAIMS

19. (Previously Presented) A suspension comprising:

a suspension bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance applied as a surface finishing material, the surface finishing material being heat treated prior to bonding to a surface; and

a slider bonding pad initially without bonding substance coupled to said suspension such that the bonding substance on said suspension bonding pad is reflowed so as to electrically couple the suspension bonding pad and the slider bonding pad, wherein the slider bonding pad enables the reuse of the suspension by removing the connection between a slider and the slider bonding pad with heat treatment.

20. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is solder.

21. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is a conductive polymer.

22. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is an adhesive.

Application No.: 09/741,684  
Amendment After Final dated: January 16, 2007  
Reply to Office Action dated: November 14, 2006

23. (Previously Presented) The suspension as claimed in claim 19, wherein said bonding substance is a film.

24. (Previously Presented) The suspension as claimed in claim 20, wherein a bump height for the solder is approximately 50-300  $\mu\text{m}$ , and a bump diameter for the solder is less than 180  $\mu\text{m}$ .

25-30 (Cancelled)